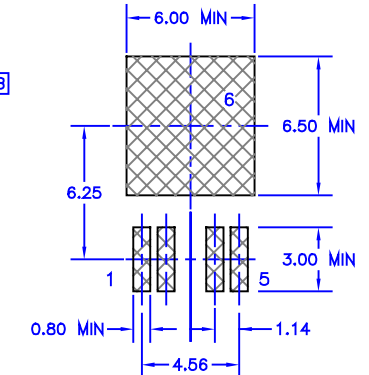
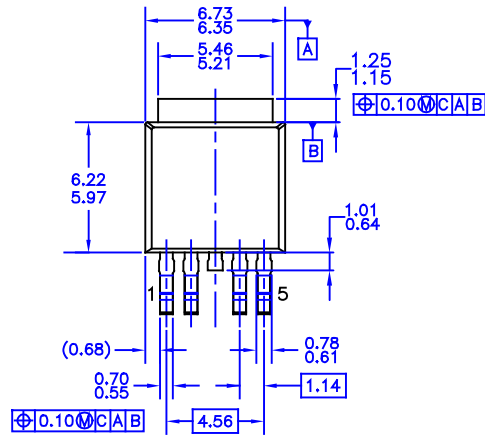
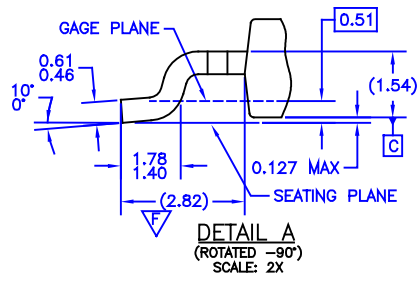
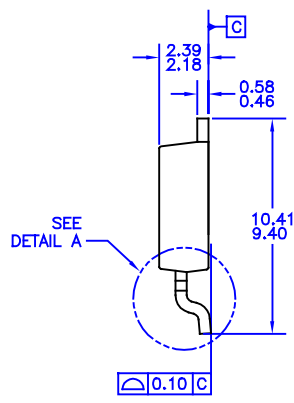
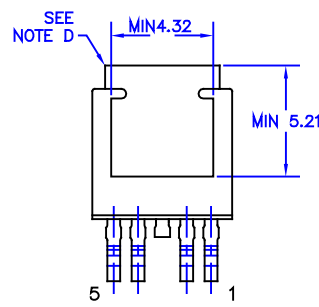


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REVISIONS			
LT#	DESCRIPTION	E.C.N.	DATE
1	RELEASE TO DOCUMENT CONTROL	-	05APR2006
			BY/APPD OS JEON



LAND PATTERN RECOMMENDATION



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE CONFORMS TO JEDEC, TO-252 ISSUE E, VARIATION AD, DATED JUNE. 2004.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.
 - E) DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994
 - F) EXCEPTION TO TO-252 STANDARD
 - G) FILENAME: TO252B05REV1

TO252B05REV1

APPROVALS	DATE	 BUCEON KOREA TO-252 MOLDED, 5LD JEDEC TO-252, AD
DRAWN: S. W LIM	05APR2006	
CHECKED: S. W LIM	05APR2006	
APPROVED: M.K JONG	05APR2006	
O.S JEON	05APR2006	
		SCALE: 1:1 FORMERLY: N/A
		SIZE: NA DRAWING NUMBER: MKT-T0252B05 REV: 1 SHEET: 1 OF 1